

Registration by fax

+ 49 6732 935 123

- I will attend the symposium „Wafer Level Optics 2019“ as guest
- I will attend the symposium „Wafer Level Optics 2019“ as sponsor

Title, Last name, First name

Company

E-Mail

Street (invoice address)

ZIP Code, City (invoice address)

Signature

With my signature I accept the terms and conditions of Photonics Hub GmbH (available at www.photonics-hub.de/kontakt/agb).

Note: According to Art 6 GDPR (EU General Data Protection Regulation) we inform you about the electronic storage of your data and the processing in the automatic procedure.

Online registration

www.photonics-hub.de/Veranstaltungen

Attendance Fee

- Members of German Photonic Innovation Networks **230,00 € pp**
(+19% VAT, corr. 273,70 € gross)
- Non-members **280,00 € pp**
(+19% VAT, corr. 333,20 € gross)
- Sponsor **370,00 €**
(+19% VAT, corr. 440,30 € gross)

The **Sponsor Package** includes:

- Attendance fee for 1 participant
- Table top space for exhibition during breaks (table size 140 cm x 70 cm)
- Space for 1 roll-up (max. width 85 cm)
- Logo on event flyer and website

Venue

Schenck Technologie- und Industriepark GmbH
Landwehrstraße 55
D-64293 Darmstadt
Germany



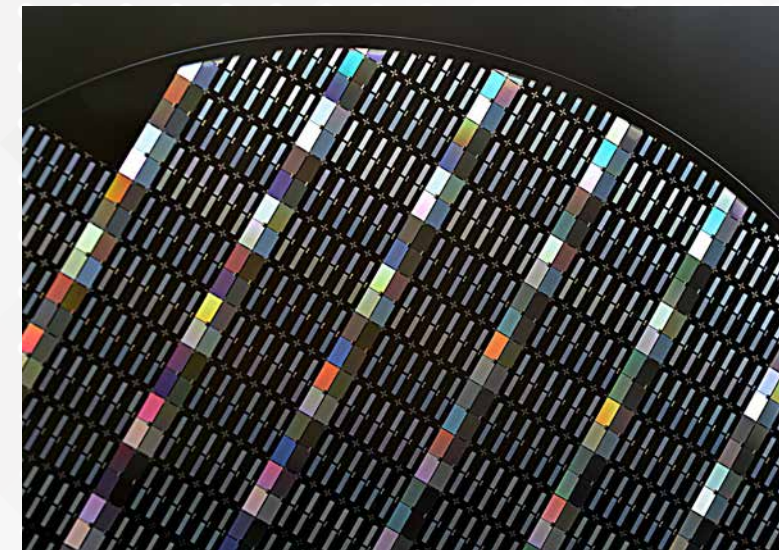
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Photonics
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Photonics Hub Symposium

Wafer Level Optics 2019



Courtesy of SUSS MicroOptics

26 March 2019
in Darmstadt

Wafer-Level Optics 2019

Due to their small size and competitive costs-to-performance ratio wafer level optics products have found their way into various markets like consumer electronics or automotive. New technological developments and an increasing demand for high volume production puts wafer level optics in the focus of industry and research alike.

The "Photonics Hub Symposium - Wafer-Level Optics 2019" will offer a platform to promote the dialogue and discussion between engineers, researchers and users in the field of innovative wafer-level optics technologies for manufacturing, metrology and application

Our Sponsors



Preliminary program

09:30 **Welcome**

09:35 **Wafer-Level Optics – Manufacturing and Applications**

Dr. Reinhard Völkel, SUSS MicroOptics

10:00 **Additive manufacturing for the production of micro-optics**

Dr. Michael Thiel, Nanoscribe GmbH

10:25 **High volume infrared optics production - Challenges in molding chalcogenide glass on wafer scale**

Jan-Helge Staasmeyer, Fraunhofer-Institut für Produktionstechnologie (IPT)

10:50 **Coffee Break**

11:20 **Technological challenges in mold making and in the replication of pressed wafer-level optics made of glass**

Guido Pongs, Aixtooling GmbH

11:45 **Wafer-Level manufacturing of micro-optical systems**

Dr. Robert Leitel, Fraunhofer-Institut für Angewandte Optik und Feinmechanik (IOF)

12:10 **Integration of Wafer Level Optics into Advanced Packages**

Robert Giertz, AEMtec GmbH

12:35 **Lunch break**

13:35 **What can a wavefront sensor tell us about waver level optics**

Dr. Christian Brock, OPTOCRAFT GmbH

14:00 **Wavefront metrology for Wafer Level Optics - WF-M as quality control for face recognition, fiber input, and cell phone lenses**

Christian Domagalski, TRIOPTICS GmbH

14:25 **UV curing materials for Waver Level Optics**

Dr. Markus Brehm, DELO Industrie Klebstoffe GmbH & Co. KGaA

14:50 **Applications of Special Glass in Wafer Level Optics**

Dr. Guangjun Zhang, SCHOTT (Shanghai) Precision Material & Equipment International Trading Co., Ltd.

15:15 **Coffee Break**

15:45 **Wafer level production of optical interference coatings: Where Optics meets Semiconductors**

Dr. Silvia Schwyn Thoeny, Evatec Europe GmbH

16:10 **Analysis of high resolution camera lens**
Fanyue Li, Huatian Huichuang technology (Xi'an) Co., Ltd.

16:35 **PHOCNOSIS - A room-temperature bonded optofluidic chip for Point-of-Care testing application**

Dr. Vanessa Zamora Gómez, Fraunhofer-Institut für Zuverlässigkeit und Mikrointegration (IZM)

17:00 **End of event**

Courtesy of SUSS MicroOptics

Courtesy of Fraunhofer IPT

